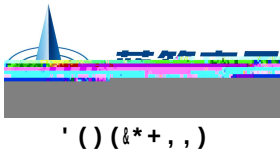


' () (& * + , , ,)



描述&&-&&' .1430C=05>1&

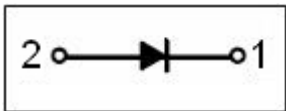
SOD-323
Schottky Diode in a SOD-323 Plastic Package.
&

特征&&-&&8.;=D3.1&

&

用途&&-&&(CC:04;=05>1&&

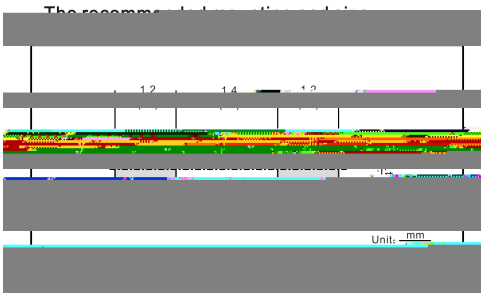
内部等效电路&&-&&, ED0/;:.>=9034D0=&



引脚排列&&-&&F0>>0>B&

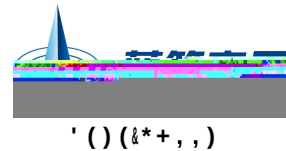


PIN1:Cathode PIN2:Anode



放大及印章代码&&-&&78,&9:;110<04;=05>1&?&@;3A0>B&

Model	RB501V-40
Marking	4



极限参数 (H15:D-.&@; I0 J D J & ; =0>B1K); LG °C M&

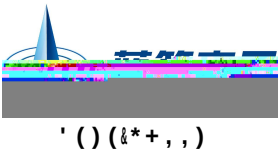
&

Parameter	Symbol	Rating	Unit
Maximum recurrent peak reverse voltage	V_{RM}	45	V
DC reverse voltage	V_R	40	V
Continuous forward current	I_O	0.1	A
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	13	A
Capacitance between terminals VR=10V, f=1MHz	C_T	6	pF
Junction Temperature	T_j	125	°C
Storage Temperature	T_{stg}	-55 ~ +150	°C

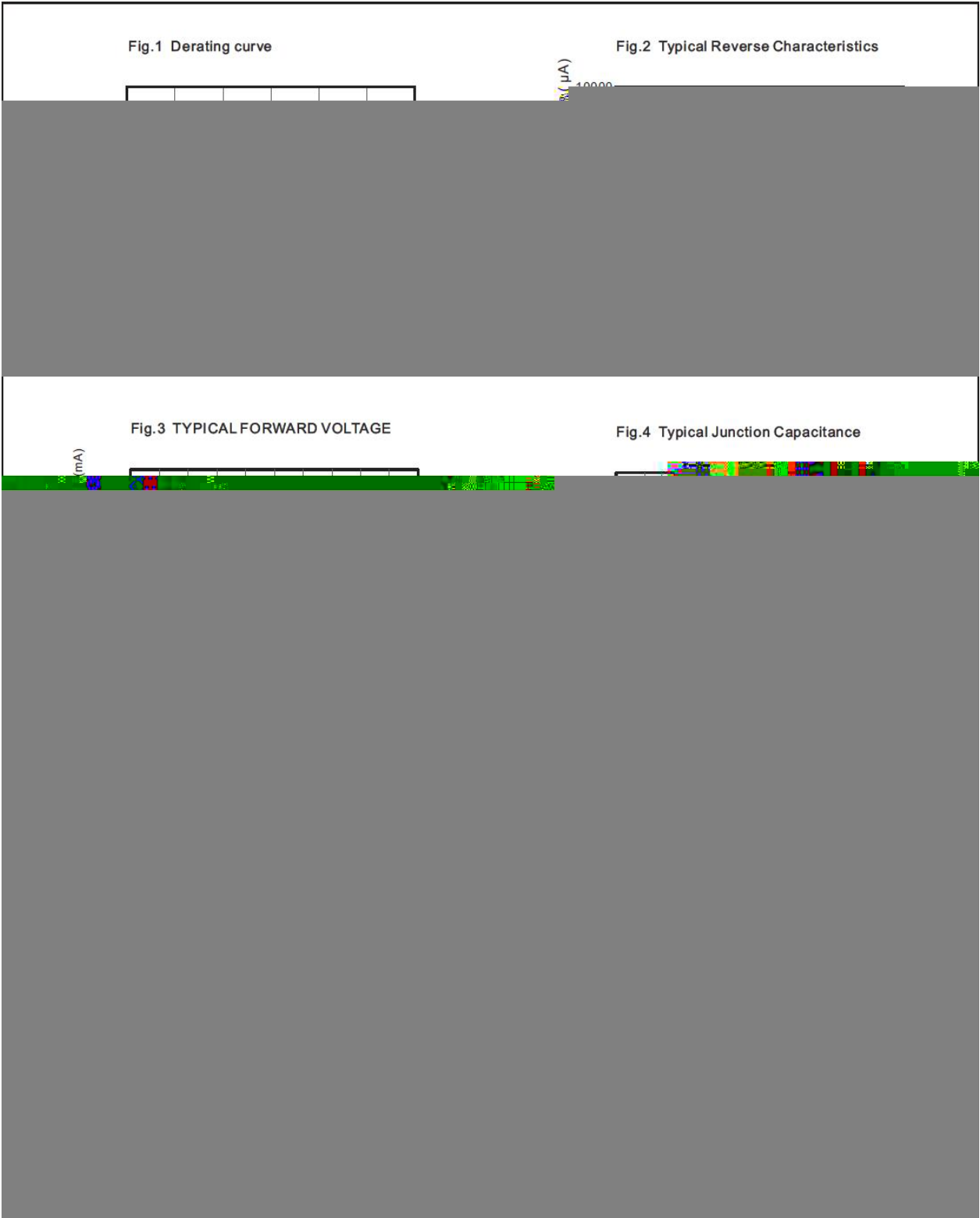
电性能参数 (H15:D-.&@; I0 J D J & ; =0>B1K); LG °C M&

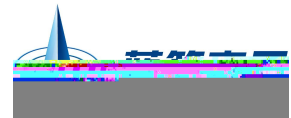
&

Parameter	Symbol	Test Conditions	Rating	Unit
Maximum Forward Voltage	V_F	$I_F=10mA$	0.34	V
		$I_F=100mA$	0.55	
Reverse Leakage Current	I_R	$V_R=10V$	30	uA

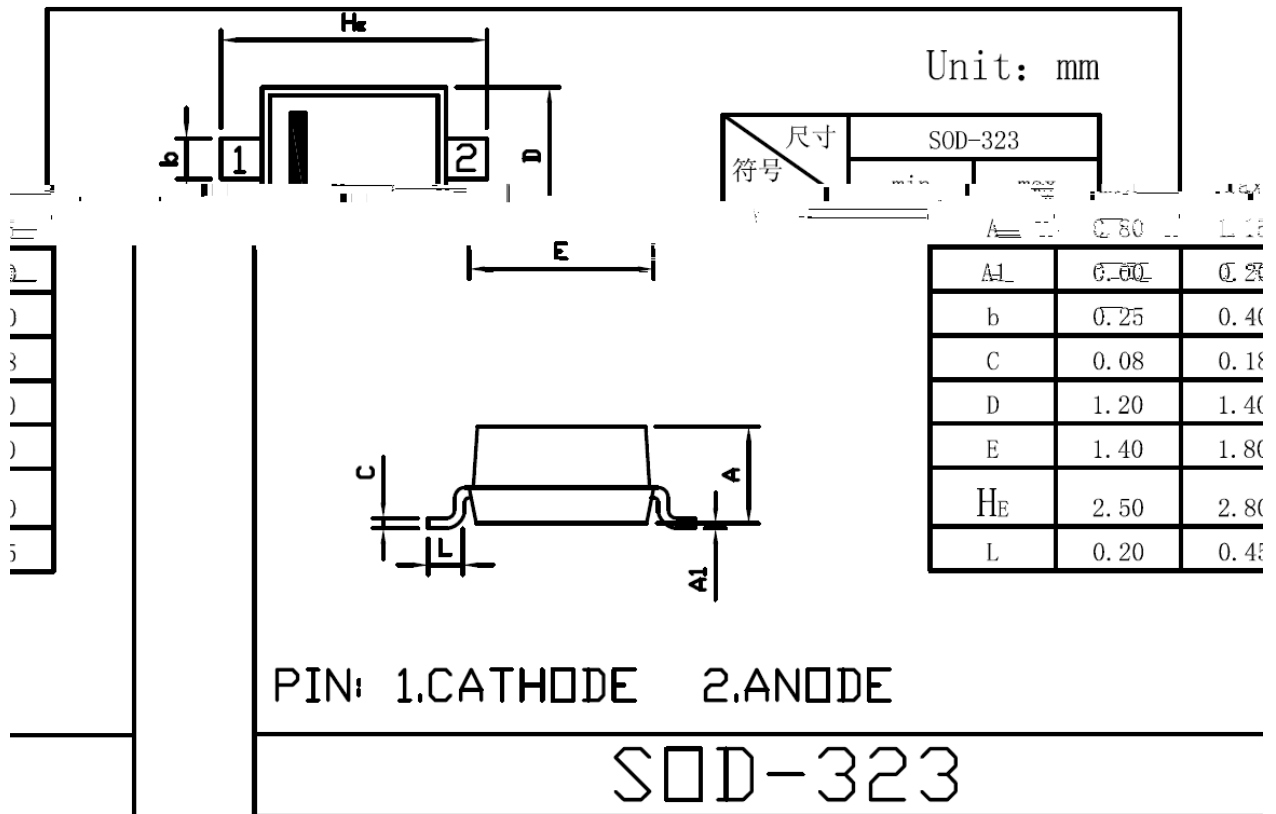


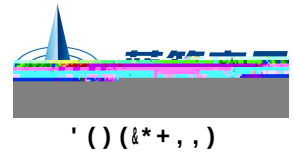
电参数曲线图&&-&& , :.4=304;:&97;3;4=.301=04&9D3/ .&



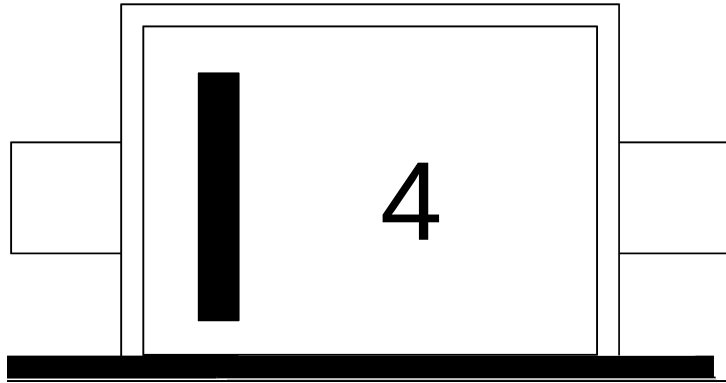


外形尺寸图 4A; B. 0 J .>105>1





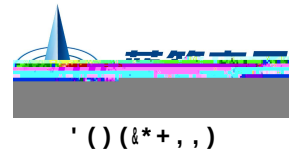
印章说明& & @ ; 3A0>B&0>1=3D4=05>1&



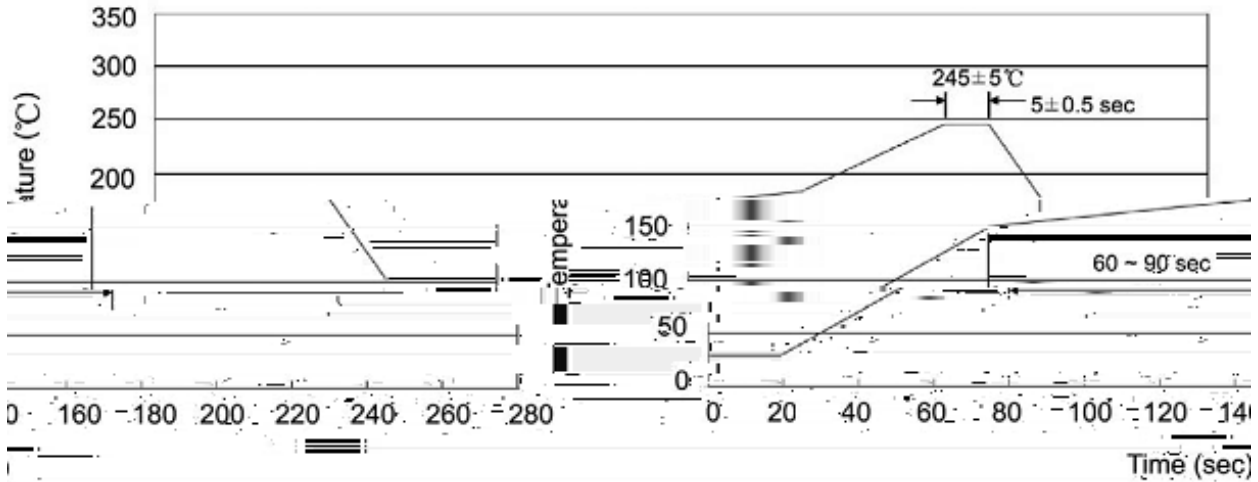
|

Note:

| | | | |



回流焊温度曲线图(无铅) & Temperature Profile for Lead-free



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

焊

温度：260±5°C 时间：10±1 sec.

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

卷盘包装 / REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOD-323	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

用说明 & Q5=04.1